P/N 97-68340 for Motorola 68340
144-Pin QFP-to-PGA Adapter

FEATURES

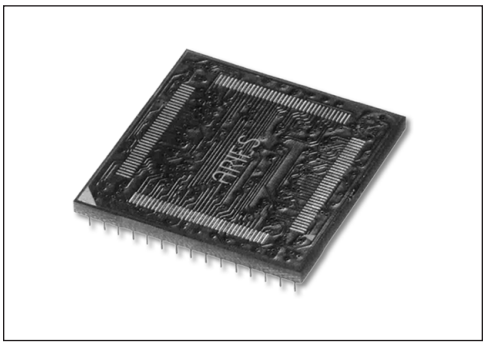
- Convert surface mount QFP packages to a 15x15 PGA footprint
- Reduce costs by using less expensive QFP packages to replace PGA footprints in existing designs
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact
- Consult factory for panelized form or for mounting of consigned chips

GENERAL SPECIFICATIONS

- ADAPTER BODY: FR-4, 0.062 [1.58] thick, with 1-oz. min. Cu traces
- PADS: bare Cu protected with ENIG or immersion white Sn to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000 ASTM-B16-00
- PIN PLATING: 200µ [5.08µ] min. Sn per ASTM B 545 Type 1 or Sn/Pb 93/7 per ASTM B 545 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.062 ±0.003 [1.58 ±0.08] dia.
- Will plug into standard PGA sockets



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE**: Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

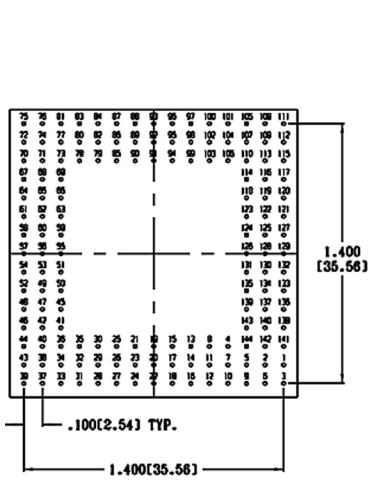
P/N 97-68340
P/N 97-68340-P for Panelized Form
P/N 145-PGM15024-30 for Wire Wrap PGA Socket

ALL DIMENSIONS: INCHES [MILLIMETERS]

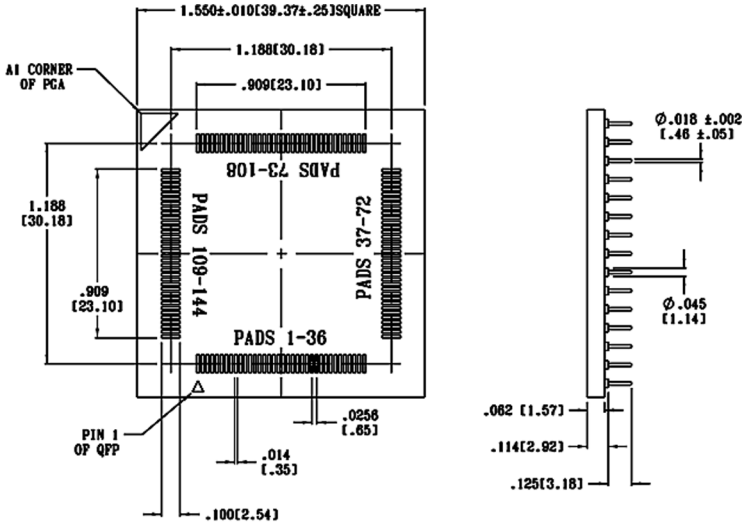
ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW ±0.003 [±0.08]
PIN-TO-PIN ±0.003 [±0.08] NON-CUMULATIVE

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



X-RAY VIEW TOP SIDE
QFP PAD ASSIGNMENT



TOP (QFP) SIDE

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